

In the Claims:

Please amend claims 32-34 so as to renumber claims 32-34 as claims 30-32, respectively, as directed by the Examiner. Please amend claims 1 and 13. Please cancel claims 24-29. The claims are as follows:

1. (Currently amended) A method for controlling a process on a substrate comprising:
providing the substrate, the substrate having an upper surface, an opposite lower surface, and an outer edge between the upper and lower surfaces;
processing the upper surface of the substrate with a first fluid;
directing a second fluid against a portion of the lower surface proximate to the outer edge of the substrate, wherein said second fluid flows adjacent to the outer edge of the substrate, and wherein said second fluid further flows toward the outer edge of the substrate while in direct mechanical contact with the lower surface of the substrate; and
controlling the temperature of said second fluid in order to affect a processing of an edge region of the upper surface of the substrate.
2. (Original) The method of claim 1, wherein the substrate is a semiconductor wafer.
3. (Original) The method of claim 1, wherein the second fluid comprises a gas.
4. (Canceled)

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5. (Previously presented) The method of claim 1 wherein controlling the temperature of said second fluid comprises increasing the temperature of the second fluid above an ambient temperature.

6. (Previously presented) The method of claim 1, wherein processing the upper surface of the substrate comprises etching said upper surface.

7-11. (Canceled)

12. (Original) The method of claim 1, further including rotating the substrate.

13. (Currently amended) A method for processing a substrate having an upper surface, an opposite lower surface and an outer edge between the upper and lower surfaces, comprising:

providing a chuck for elevating the substrate above a top surface of said chuck using a suspension fluid, said suspension fluid delivered from an annular opening in said upper surface of said chuck, said annular opening located proximate to an edge of said chuck, said suspension fluid flowing toward the outer edge of the substrate while in direct mechanical contact with the lower surface of the substrate proximate to the outer edge of the substrate;

delivering a processing fluid to the upper surface of the substrate; and

maintaining the temperature of said suspension fluid at a temperature different from an ambient temperature while delivering said processing fluid.

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14-15. (Canceled)

16. (Original) The method of claim 13, further including rotating said chuck.

17-20. (Canceled)

21. (Previously presented) The method of claim 1, further comprising providing a temperature sensor that measures the temperature of the second fluid near the outer edge of the substrate.

22. (Previously presented) The method of claim 21, further comprising providing a controller for displaying the temperature measured by the temperature sensor, said controller being electrically connected to the temperature sensor.

23. (Previously presented) The method of claim 22, wherein controlling the temperature of the second fluid comprises heating or cooling the second fluid by a thermal device that is electrically connected to the controller, said thermal device being a heater or a chiller.

24-29. (Canceled)

[[32]] 30. (Currently amended) The method of claim 13, further comprising providing a temperature sensor that measures the temperature of the suspension fluid near the outer edge of

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the substrate.

[[33]] 31. (Currently amended) The method of claim [[32]] 30, further comprising providing a controller for displaying the temperature measured by the temperature sensor, said controller being electrically connected to the temperature sensor.

[[34]] 32. (Currently amended) The method of claim [[32]] 30, wherein maintaining the temperature of the suspension fluid comprises heating or cooling the suspension fluid by a thermal device that is electrically connected to the controller, said thermal device being a heater or a chiller.